

# NTC thermistors for temperature measurement

Probe assemblies

Series/Type: B57504K Date: January 2018

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B57504K

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#### Temperature measurement

#### **Probe assemblies**

#### Applications

 Temperature measurement in household appliances (e.g. dryers, dish washers, small appliances)

#### Features

- NTC thermistor potted in a medium-resistant stainless steel case
- Short thermal response time in water
- Wire heat-resistant up to 125 °C (XLPE-insulated wire)

#### Options

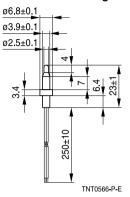
Alternative casing, cable lengths, cable material (PTFE), R/T characteristics and connectors available on request.

#### **Delivery mode**

Bulk

#### General technical data

#### Dimensional drawing



Dimensions in mm Approx. weight 2.3 g

Climatic category	(IEC 60068-1)		20/125/42	
Upper category temperature	(wire)		125	°C
Maximum operating temperature	(sensor head)	T <sub>op,max</sub>	150	°C
Resistance tolerance		$\Delta R_{\rm R}/R_{\rm R}$	±2	%
Rated temperature		T <sub>R</sub>	70	°C
Dissipation factor	(in air)	$\delta_{\text{th}}$	approx. 2	mW/K
Thermal time constant	(in water)	$\tau_{a}$	< 2	s
Insulation resistance	(V = 500 V DC)	R <sub>ins</sub>	> 100	MΩ
Test voltage	(t = 1 s)	V <sub>test</sub>	1250	V AC

#### Electrical specification and ordering codes

R <sub>70</sub> Ω	R <sub>25</sub> Ω	No. of R/T characteristic	B <sub>25/100</sub> K	Ordering code
2055	10000	7003	3625 ±0.8%	B57504K0103A009

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#### **Reliability data**

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2	Storage at max. operating temperature T: 150 °C t: 168 h Medium: air	< 3%	No visible damage
Storage in coldness		Storage at lower category temperature T: -20 °C t: 1000 h Medium: air	< 3%	No visible damage
Storage in damp heat, steady state		Temperature of air: 60 °C Relative humidity of air: 93% Duration: 1000 h	< 3%	No visible damage
Rapid temperature cycling (in water)		Lower test temperature: 15 °C Upper test temperature: 96 °C Dwell time: 30 s Time to change from lower to upper temperature: <10 s Number of cycles: 1000 Medium: water	< 3%	No visible damage
Vibration resistance	IEC 60068-2-6	Frequency range: 10 to 2000 Hz Amplitude: 1.5 mm, 10 $g$ Linear sweep; X, Y and Z direction Duration: $3 \times 2$ h	< 3%	No visible damage
Natural falling test		Drop sensor 3 times from a height of 75 cm spontaneously onto hard surface	< 3%	No visible damage
Boiling test		Storage at 96 °C in water for 6 h, then natural cooling for 16 h	< 3%	No visible damage

#### Note

- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals).
- Avoid dewing and condensation unless thermistor is specified for these conditions.

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#### **R/T characteristics**

R/T No.	7003							
T (°C)	B <sub>25/100</sub> = 3625 K		T (°C)	B <sub>25/100</sub> = 3625 K		T (°C)	B <sub>25/100</sub> = 3625 K	
	R <sub>T</sub> /R <sub>25</sub>	α (%/K)		R <sub>T</sub> /R <sub>25</sub>	α (%/K)		R <sub>T</sub> /R <sub>25</sub>	α (%/K)
-55.0	63.225	6.7	65.0	0.24049	3.2	185.0	0.013448	1.8
-50.0	45.46	6.5	70.0	0.20553	3.1	190.0	0.012297	1.8
-45.0	33.07	6.3	75.0	0.17637	3.0	195.0	0.011265	1.7
-40.0	24.324	6.0	80.0	0.15195	2.9	200.0	0.010338	1.7
-35.0	18.081	5.8	85.0	0.13141	2.9	205.0	0.009504	1.7
-30.0	13.575	5.6	90.0	0.11406	2.8	210.0	0.0087516	1.6
-25.0	10.29	5.4	95.0	0.099352	2.7	215.0	0.0080718	1.6
-20.0	7.8716	5.3	100.0	0.086837	2.7	220.0	0.0074567	1.6
-15.0	6.0739	5.1	105.0	0.076149	2.6	225.0	0.0068989	1.5
-10.0	4.7258	4.9	110.0	0.066989	2.5	230.0	0.0063925	1.5
-5.0	3.7062	4.8	115.0	0.059112	2.5	235.0	0.0059318	1.5
0.0	2.9287	4.6	120.0	0.052316	2.4	240.0	0.005512	1.5
5.0	2.3311	4.5	125.0	0.046433	2.4	245.0	0.005129	1.4
10.0	1.8684	4.4	130.0	0.041327	2.3	250.0	0.004779	1.4
15.0	1.5075	4.2	135.0	0.03688	2.3	255.0	0.0044586	1.4
20.0	1.224	4.1	140.0	0.032998	2.2	260.0	0.004165	1.4
25.0	1.0000	4.0	145.0	0.029598	2.2	265.0	0.0038955	1.3
30.0	0.82176	3.9	150.0	0.026612	2.1	270.0	0.0036478	1.3
35.0	0.67909	3.8	155.0	0.023984	2.1	275.0	0.0034199	1.3
40.0	0.56422	3.7	160.0	0.021665	2.0	280.0	0.0032098	1.3
45.0	0.47122	3.6	165.0	0.019613	2.0	285.0	0.003016	1.2
50.0	0.3955	3.5	170.0	0.017793	1.9	290.0	0.002837	1.2
55.0	0.33355	3.4	175.0	0.016176	1.9	295.0	0.0026714	1.2
60.0	0.2826	3.3	180.0	0.014735	1.8	300.0	0.002518	1.2

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#### Cautions and warnings

#### General

See "Important notes" on page 2.

#### Storage

- Store thermistors only in original packaging. Do not open the package prior to processing.
- Storage conditions in original packaging: storage temperature -25 °C ... +45 °C, relative humidity ≤75% annual mean, <95% maximum 30 days per annum, dew precipitation is inadmissible.</p>
- Do not store thermistors where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or components may stick together, causing problems during mounting.
- Avoid contamination of thermistor surface during storage, handling and processing.
- Avoid storage of thermistors in harmful environments like corrosive gases (SO<sub>x</sub>, Cl etc).
- Use the components as soon as possible after opening the original packaging.
- Solder thermistors within the time specified after shipment from EPCOS. For leaded components this is 24 months, for SMD components with nickel barrier termination 12 months, for leadless components this is 12 months, for SMD components with AgPd termination 6 months.

#### Handling

- NTC thermistors must not be dropped. Chip-offs or any other damage must not be caused during handling of NTCs.
- Do not touch components with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.
- Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

#### Bending / twisting leads

A lead (wire) may be bent at a minimum distance of twice the wire's diameter plus 4 mm from the component head or housing. When bending ensure the wire is mechanically relieved at the component head or housing. The bending radius should be at least 0.75 mm.

#### Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

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#### Mounting

- Ensure that no thermo-mechanical stress occurs due to production processes (curing or overmolding processes) when thermistors are sealed, potted or overmolded or during their subsequent operation. The maximum temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing/potting compound and plastic material) are chemically neutral.
- Electrodes/contacts must not be scratched or damaged before/during/after the mounting process.
- Contacts and housing used for assembly with the thermistor must be clean before mounting.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand the temperature.
- Avoid contamination of the thermistor surface during processing.
- The connections of sensors (e.g. cable end, wire end, plug terminal) may only be exposed to an environment with normal atmospheric conditions.
- Tensile forces on cables or leads must be avoided during mounting and operation.
- Bending or twisting of cables or leads directly on the thermistor body is not permissible.
- Avoid using chemical substances as mounting aids. It must be ensured that no water or other liquids enter the NTC thermistors (e.g. through plug terminals). In particular, water based substances (e.g. soap suds) must not be used as mounting aids for sensors.
- The use of no-clean solder products is recommended. In any case mild, non-activated fluxes should be used. Flux residues after soldering should be minimized.

#### Operation

- Use thermistors only within the specified operating temperature range.
- Use thermistors only within the specified power range.
- Environmental conditions must not harm the thermistors. Only use the thermistors under normal atmospheric conditions or within the specified conditions.
- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. perfluoropolyethers such as Galden).
- Avoid dewing and condensation unless thermistor is specified for these conditions.
- Bending or twisting of cables and/or wires is not permissible during operation of the sensor in the application.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by malfunction.

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.

#### Display of ordering codes for EPCOS products

The ordering code for one and the same EPCOS product can be represented differently in data



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sheets, data books, other publications, on the EPCOS website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes

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#### Symbols and terms

Symbol	English	German
A	Area	Fläche
AWG	American Wire Gauge	Amerikanische Norm für Drahtquerschnitte
В	B value	B-Wert
B <sub>25/100</sub>	B value determined by resistance	B-Wert, ermittelt durch Widerstands-
	measurement at 25 °C and 100 °C	messungen bei 25 °C und 100 °C
C <sub>th</sub>	Heat capacitance	Wärmekapazität
I	Current	Strom
Ν	Number (integer)	Anzahl (ganzzahliger Wert)
P <sub>25</sub>	Maximum power at 25 °C	Maximale Leistung bei 25 °C
$P_{diss}$	Power dissipation	Verlustleistung
P <sub>el</sub>	Electrical power	Elektrische Leistung
P <sub>max</sub>	Maximum power within stated	Maximale Leistung im
	temperature range	angegebenenTemperaturbereich
$\Delta R_{B}/R_{B}$	Resistance tolerance caused by	Widerstandstoleranz, die durch die
	spread of B value	Streuung des B-Wertes verursacht wird
R <sub>ins</sub>	Insulation resistance	Isolationswiderstand
R₽	Parallel resistance	Parallelwiderstand
R <sub>R</sub>	Rated resistance	Nennwiderstand
$\Delta R_R/R_R$	Resistance tolerance	Widerstandstoleranz
R <sub>s</sub>	Series resistance	Serienwiderstand
R <sub>τ</sub>	Resistance at temperature T ( $a = B$ = resistance at 25 °C)	Widerstand bei Temperatur T (7 R. R. $=$ Widerstand bei 25 °C)
	(e.g. $R_{25}$ = resistance at 25 °C)	(z.B. $R_{25}$ = Widerstand bei 25 °C)
Т	Temperature	Temperatur
ΔT	Temperature tolerance	Temperaturtoleranz
t T	Time	Zeit
T <sub>A</sub> T	Ambient temperature	
T <sub>max</sub>	Upper category temperature	Obere Grenztemperatur
T <sub>min</sub>	Lower category temperature	(Kategorietemperatur) Untere Grenztemperatur
I min	Lower category temperature	(Kategorietemperatur)
T <sub>op</sub>	Operating temperature	Betriebstemperatur
T <sub>B</sub>	Rated temperature	Nenntemperatur
T <sub>surf</sub>	Surface temperature	Oberflächentemperatur
V	Voltage	Spannung
V <sub>ins</sub>	Insulation test voltage	Isolationsprüfspannung
V <sub>op</sub>	Operating voltage	Betriebsspannung
V <sub>test</sub>	Test voltage	Prüfspannung



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Symbol	English	German
α	Temperature coefficient	Temperaturkoeffizient
$\Delta$	Tolerance, change	Toleranz, Änderung
$\delta_{\text{th}}$	Dissipation factor	Wärmeleitwert
$ au_c$ $ au_a$	Thermal cooling time constant Thermal time constant	Thermische Abkühlzeitkonstante Thermische Zeitkonstante

#### Abbreviations / Notes

Symbol	English	German
SMD	Surface-mounted devices	Oberflächenmontierbares Bauelement
*	To be replaced by a number in ordering codes, type designations etc.	Platzhalter für Zahl im Bestellnummern- code oder für die Typenbezeichnung.
+	To be replaced by a letter.	Platzhalter für einen Buchstaben.
	All dimensions are given in mm.	Alle Maße sind in mm angegeben.
	The commas used in numerical values denote decimal points.	Verwendete Kommas in Zahlenwerten bezeichnen Dezimalpunkte.



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